SEAT	No	

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[120]

SARDAR PATEL UNIVERSITY

M.Sc. 4th Semester (Surface Coating Technology) (CBCS) Examination Tuesday, April 10th, 2018
Time: 02:00 pm to 05:00 pm

Course No.: PS04CSCT01

Subject: Technology of Resins for Surface Coatings-II

	Total Marks	: 70	
V.B. (Marks allotted to the question are on its RHS Illustrate your answers wherever necessary with the help of neat sketches & chemical equations 		
Q.1 [—]	Choose the correct answer from the followings:		
Q.1.1	The weight of resin containing 1 gm equivalent of Epoxide is referred to as		
	(a) Epoxy Equivalent Weight (b) Epoxy Value		
	(c) Weight per phenoxy (d) Esterification Molar Mass		
Q.1.2	can acts as a viscosity reducer and catalyst in Epoxy - polyamide cure system.	1	
	(a) Triphenyl phosphite (b) Resorcinol (c) DMP-30 (d) Triethanol amine		
Q.1.3	based liquid epoxy resins have much lower viscosities for same 'n' than their	1	
	corresponding BPA resins.		
	(a) BPF (b) Halogenated Epoxy resin (c) Epoxy Novalac resins (d) Phenoxy resins.	•	
Q.1.4	The relative reaction rates of species with isocyanates are:	1	
	1°amine > 2° amine > > Water > Urea > Urethane > Carboxyl		
	(a) Allophanate (b) Hydroxyl (c) Biuret (d) Ethers.		
Q.1.5	Reactive Polyamide resin is use as a curing agent for resin.	1	
	(a) Alkyd (b) Epoxy (c) Polyester (d) None of these.		
Q.1.6	R-NCO + H₂0 +	1	
	(a) $R-NH_2 + CO_2$ (b) $R-NH-CO-R + CO_2$ (c) $R-NH_2 + H_2O$ (d) $R-NH-CO-R + H_2O$		
Q.1.7	Film formation of Nitrocellulose lacquer is done by	1	
	(a) Solvent Evaporation & Chemical curing (b) Solvent Evaporation		
	(c) Solvent Evaporation & Oxidative Polymerization (d) Radiation Polymerization		
Q.1.8	+ 2C→Si +	1	
	(a) SiO_2 + 2 CO (b) SiO_2 + CO ₂ (c) RSiCl + H ₂ O (d) RSiCl+ 2 CO		
Q.2	Write the reasons for the following statements (<u>any seven</u>):	14	
	a. Write the structure of EDA, DETA, TETA, TEPA and PEHA		
	b. Bisphenol F based liquid epoxy resin have much lower viscosities for the same value of		
	'n' than their corresponding Bisphenol A resins?		
	c. Monofunctional acids are used in the manufacture of Polyamides.		
	d. Factors affecting pot life in Epoxy-Polyamide system. Explain in brief		
	e. Calculate the amount of Hardener required for 100 parts of epoxy resins by using		
	following data.		
	Epoxy Resins: (1) EEW = 200 (2) EEW = 250 (3) EEW = 450		
	Polyamide Hardener: Amine Value (Solid resin) = 220 mg of KOH/gm,		

% Solid (Supplied) = 70 % in Xylene. f. Aromatic Amines do not cure satisfactorily at room temperature and require acceleration. g. Write the role and types of Reactive Diluent currently find use in Epoxy resin. h. Parameters which influence curing reaction condition of Blocked Isocynates. Calculate Theoretical % NCO content for TDI, HDI and IPDI respectively. 6 Write a note on Epoxy resin not based on Bisphenol A 6 Describe the various curing agent used in epoxy coating. Explain ambient temperature cure and heat cure epoxy paints. Discuss type and curing agent used in both condition giving example. Or 6 Explain the three main chemical reaction, manufacture, properties and application of Epoxy ester resin in surface coatings. Q.4 a Describe the formation of an Epoxide moiety from Epichorohydrin and Bisphenol A 6 6 Q.4 b Write a note on a) Accelerators and solvent selection in Epoxy-Polyamide system. b) Phenoxy Resins. Or Q.4 b Write the schematic representation of the preparation of an Epoxy-Amine adduct (Aliphatic 6 DETA) and also formulate an epoxy-amine adduct (Aliphatic-DETA Adduct) having 40% solids and Amine value=393 mg of KOH/gm by using Epoxy resin (EEW=475 mg of KOH/gm, Solid = .75%) 6 Q.5 a What are Polyurethane resins? Give their classification as per ASTM standard based on their curing mechanism. Explain ASTM number 5 in detail. Write a note on Desmodur E type Pigmented one part Moisture cured Urethane (MCU). 6 Or Write a note on Polyurethane Dispersions (PUD's) 6 6 Write a note on Types of isocyanates used in Polyurethane coating. 6 Q.6 b Write a brief note on Catalysts used in Polyurethane coatings?

Or

Q.6 b Write the characteristics of silicone resins.

Q.3 a

Q.3 b

Q.3 b

Q.5 b

Q.5b

Q.6 a